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6

MCPBC, preferably with direct attachment for thermals.

Greater than 10MHz -3dB current bandwidth

Fixed 10A / V gain

50A max set-current

10mA max leakage when off

20mA accuracy

5V-10V DC < 1A power supply

Isolated input preferred

Over-power protection preferred

Each module report:
 -Temp
 -Voltage
 -Current

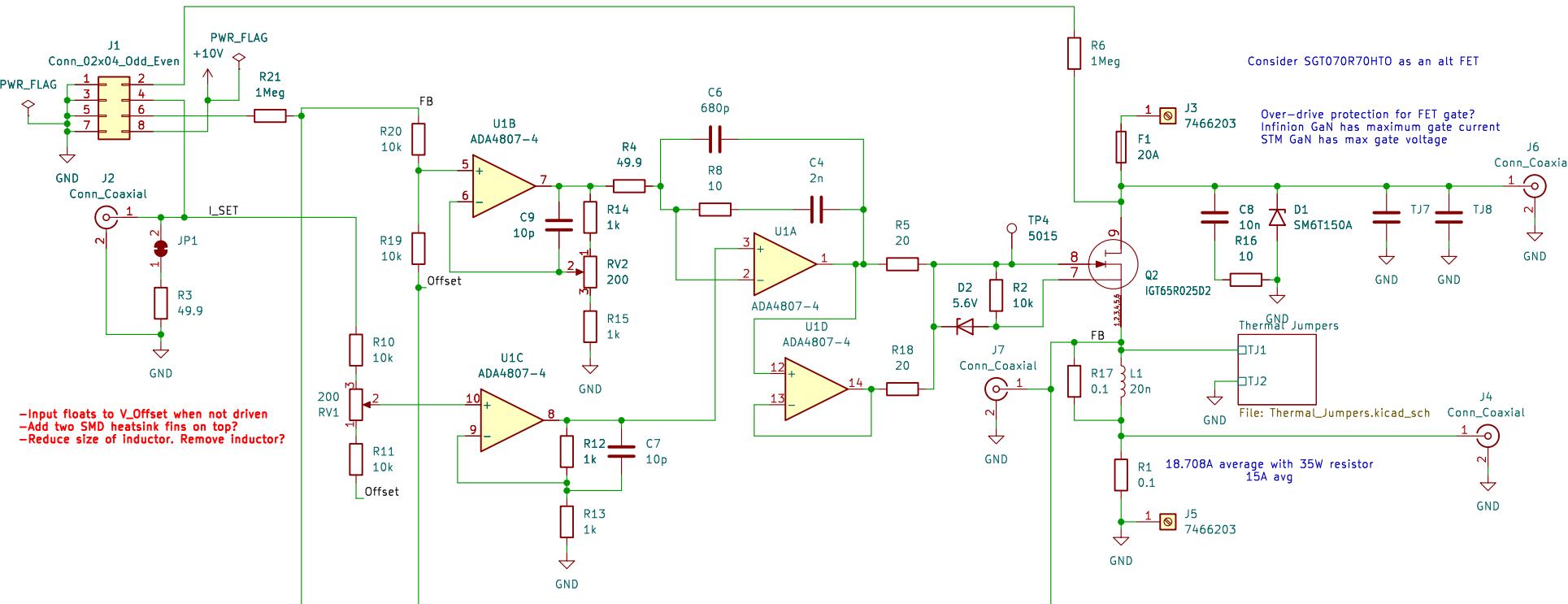
IO Considerations:
 -Pwr
 -GND
 -Set current
 -UNREG
 -Temp
 -Fault/Protect

Thermal design:
 T_{jc}, ~0.51C/W
 Solder, ~0.025 C/W
 Copper coin under FET, ~.04 C/W
 TIM: ??? Gel75, 0.2mm, -0.14 C/W

Thermal jumpers??
 TIM to heatsink, 1W/mk, 65x40mm 0.5mm, 0.19 C/W

BOM: <https://www.digikey.com/en/mylists/list/430F3M7L10>

230W abs max on FET @ 25C without external thermal impedances



A

A

B

B

C

C

D

D

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2

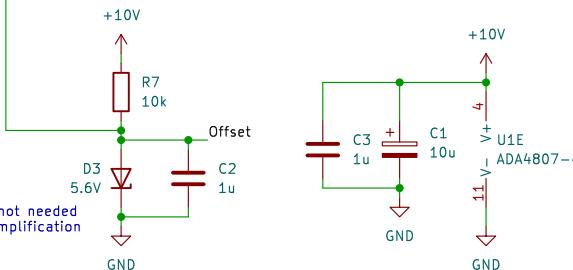
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Zener not needed
 BOM simplification



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